

Bill of Materials Change Description

MATERIALS	FROM	TO	REMARK
Die Attach	EN4900GC	EN4900GC	Same
Wire type	Gold Wire	Gold Wire	Same
Mold Compound	Hitachi 9220HF13	Sumitomo G700LYT	Changed
Lead Finish	NiPdAu	NiPdAu	Same

LFCSP 4x4 and 7x7mm

Package Outline Drawing(POD) Change Description

Body Size (mm)	Lead Count	Sawn LFCSP STATSChipPAC-China (SCC)				Sawn Type LFCSP ASE-Korea (AEK)			
		POD Spec	E-Pad Size (mm SQ.)	Lead Length (mm)	Lead Width (mm)	POD Spec	E-Pad Size (mm SQ.)	Lead Length (mm)	Lead Width (mm)
4X4	16	CP-16-23	2.10X2.10±0.15	0.60+0.10/-0.20	0.30± 0.05	CP-16-17	2.60X2.60±0.10	0.40 ± 0.05	0.30± 0.05
4X4	24	CP-24-7	2.50X2.50+0.15/-0.05	0.40 ± 0.10	0.25+0.05/-0.07	CP-24-15	2.60X2.60± 0.10	0.40 ± 0.10	0.25+0.05/-0.07
7X7	48	CP-48-10	5.10x5.10± 0.10	0.40 ± 0.05	0.25+0.05/-0.07	CP-48-13	5.60X5.60± 0.05	0.40 ± 0.10	0.25± 0.05

**ASE Korea as an Alternate Assembly Site
for Select 24L LFCSP Enhanced Products**

**Qualification Plan Summary for Select LFCSP Enhanced
Products at ASE Korea (ASE-AEK)**

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	ESTIMATED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	June 2017
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	June 2017
Electrostatic Discharge <i>Field Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	June 2017
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	June 2017
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 50	June 2017
Low Temperature Storage (LTS)	JEDEC <i>JESD22-A119</i>	3 x 77	June 2017

*Preconditioned per JEDEC/IPC J-STD-020

**ASE Korea as an Alternate Assembly Site
for Select 48L LFCSP Enhanced Products**

**Qualification Plan Summary for Select LFCSP Enhanced
Products at ASE Korea (ASE-AEK)**

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	ESTIMATED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	June 2017
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